

General Information

Series

Style Description

Features



ESD SMD Comm X7R, Ceramic, 0.33 uF, 5%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0805, 0.7 mm

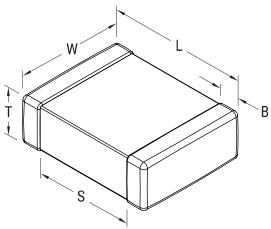
ESD SMD Comm X7R

SMD, MLCC, Temperature Stable, Electro Static Discharge,

Temperature Stable, Class II

SMD Chip

Class II



S	RoHS	Yes
	Termination	Tin
	Marking	No
	AEC-Q200	No
	Typical Component Weight	13 mg
Click here for the 3D model.	Shelf Life	78 Weeks
	MSL	1
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Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.9mm +/-0.10mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

Specifications	
Capacitance	0.33 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	1.5152 GOhms

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